

SOT2016-1

WFBGA165, very very thin profile fine pitch ball grid array package; 165 terminals; 0.5 mm pitch; 7.5 mm x 7.5 mm x 0.62 mm body

9 July 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WFBGA165
Package style descriptive code	WFBGA (very-very-thin profile fine-pitch ball grid array package)
Mounting method type	S (surface mount)
Issue date	19-06-2020
Manufacturer package code	98ASA01393D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.4	7.5	7.6	mm
package width	7.4	7.5	7.6	mm
package height	-	0.62	0.655	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	165	-	



2 Package outline

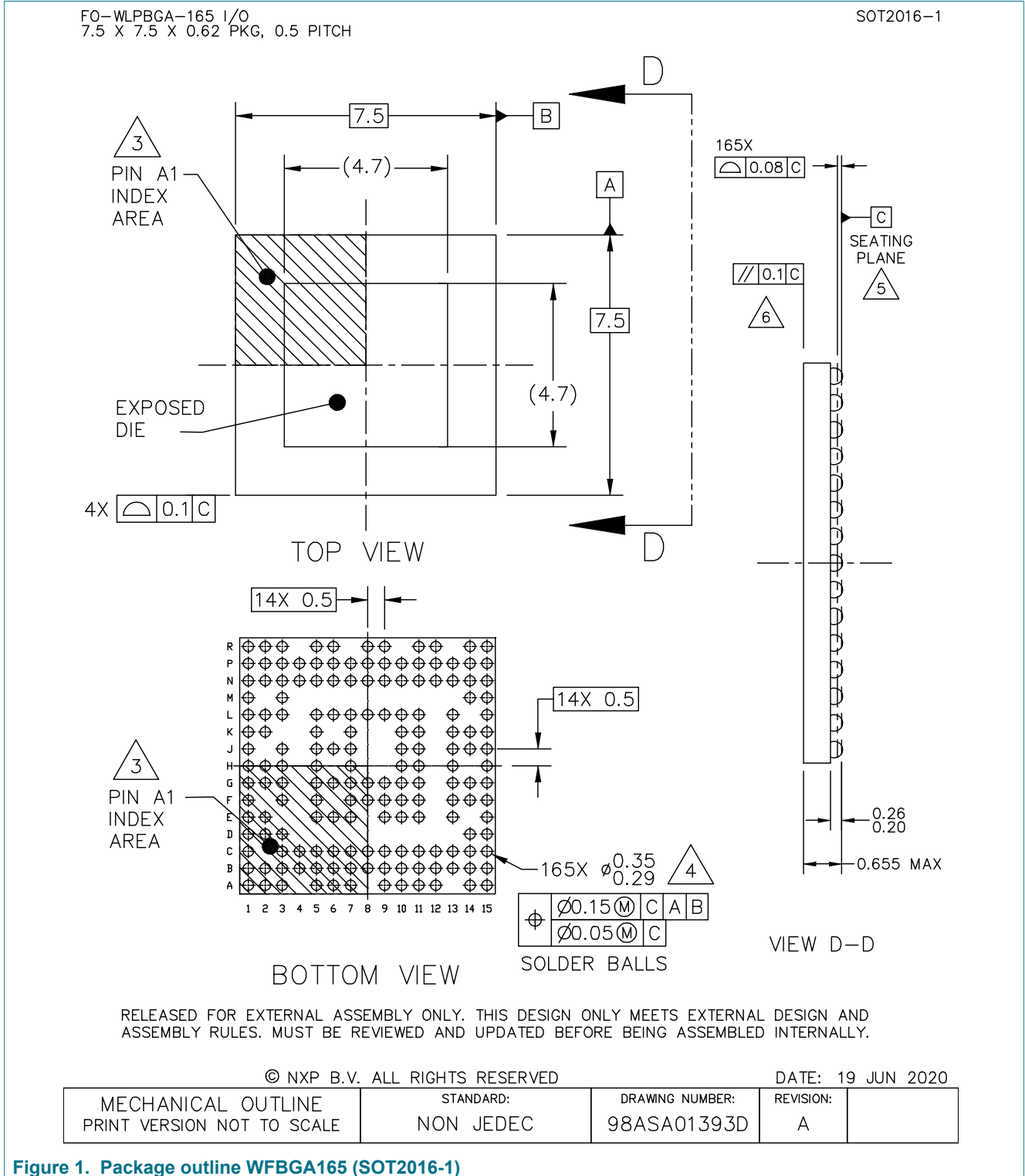


Figure 1. Package outline WFBGA165 (SOT2016-1)

WFBGA165, very very thin profile fine pitch ball grid array package; 165 terminals; 0.5 mm pitch; 7.5 mm x 7.5 mm x 0.62 mm body

3 Soldering

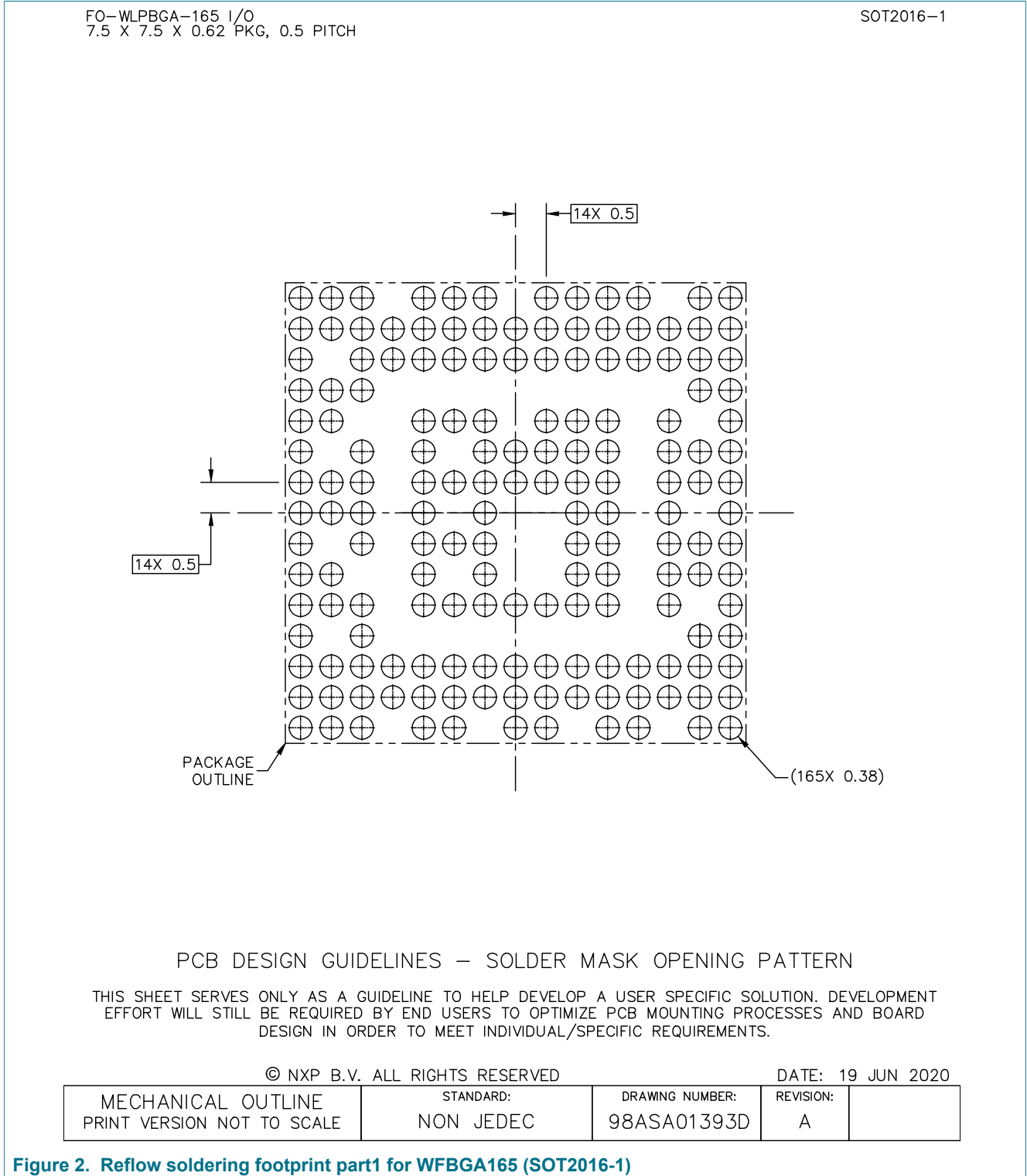
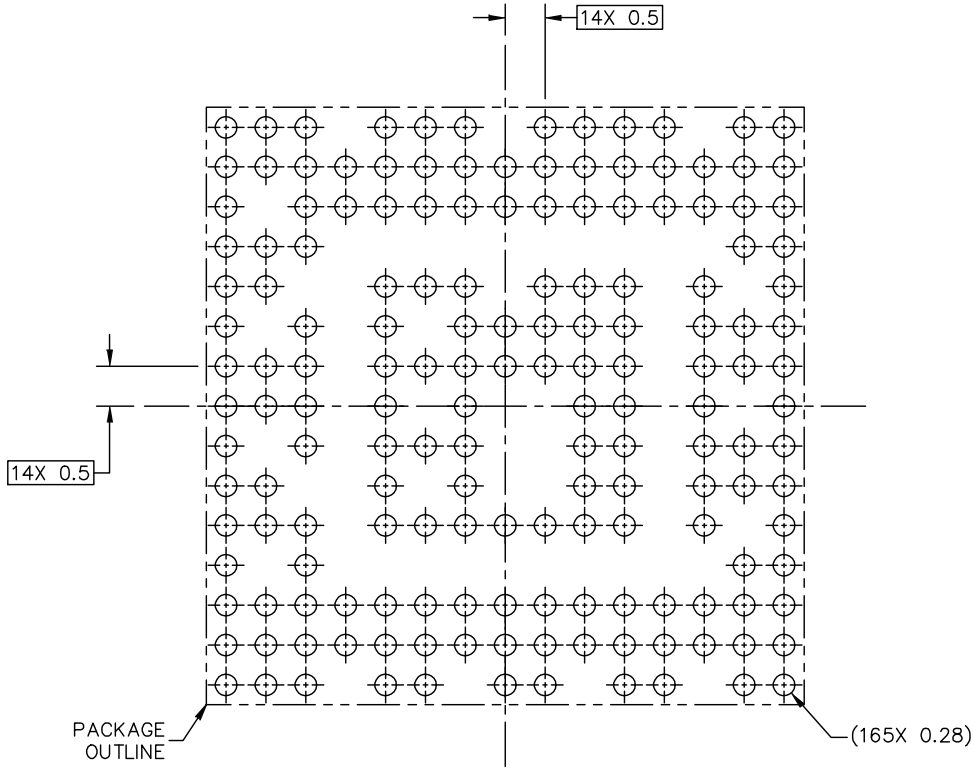


Figure 2. Reflow soldering footprint part1 for WFBGA165 (SOT2016-1)

WFBGA165, very very thin profile fine pitch ball grid array package; 165 terminals; 0.5 mm pitch; 7.5 mm x 7.5 mm x 0.62 mm body

FO-WLPBGA-165 I/O
7.5 X 7.5 X 0.62 PKG, 0.5 PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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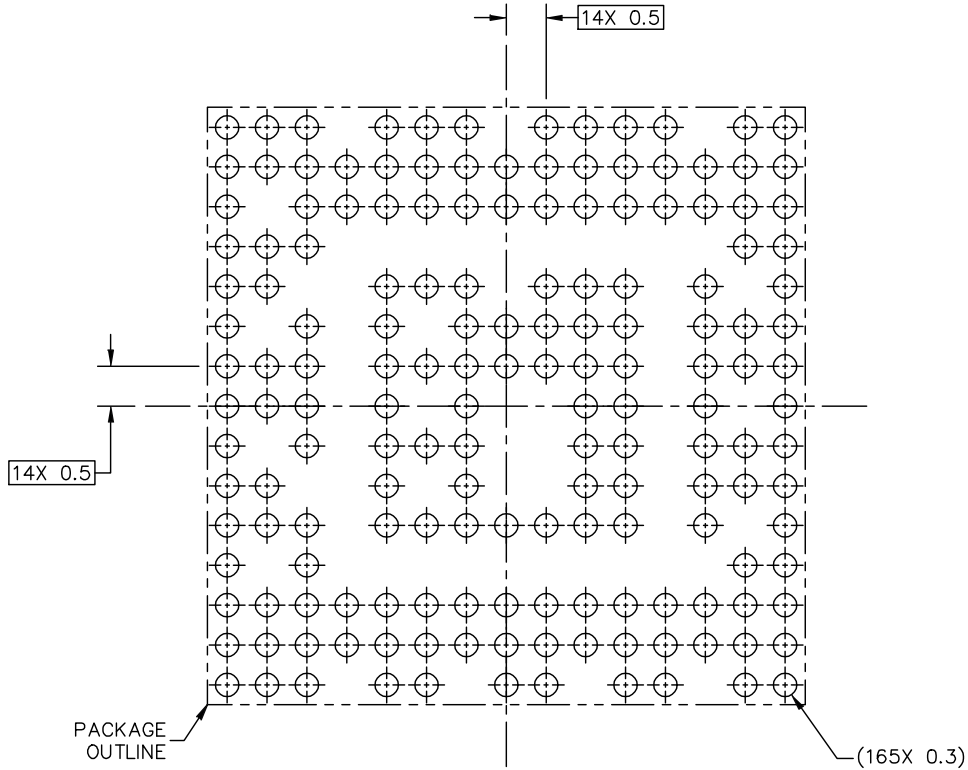
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01393D	REVISION: A	
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Figure 3. Reflow soldering footprint part2 for WFBGA165 (SOT2016-1)

WFBGA165, very very thin profile fine pitch ball grid array package; 165 terminals; 0.5 mm pitch; 7.5 mm x 7.5 mm x 0.62 mm body

FO-WLPBGA-165 I/O
7.5 X 7.5 X 0.62 PKG, 0.5 PITCH

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RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for WFBGA165 (SOT2016-1)

WFBGA165, very very thin profile fine pitch ball grid array package; 165 terminals; 0.5 mm pitch; 7.5 mm x 7.5 mm x 0.62 mm body

FO-WLPBGA-165 I/O
7.5 X 7.5 X 0.62 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note WFBGA165 (SOT2016-1)

4 Legal information

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WFBGA165, very very thin profile fine pitch ball grid array package; 165 terminals; 0.5 mm pitch; 7.5 mm x 7.5 mm x 0.62 mm body

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